TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOS III)

TPCP8201

Portable Equipment Applications Motor Drive Applications DC-DC Converter Applications

- Lead(Pb)-Free
- Low drain-source ON resistance: R_{DS} (ON) = 38 m Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 7.0 \text{ S} (typ.)$
- Low leakage current: $I_{DSS} = 10 \ \mu A (V_{DS} = 30 \ V)$
- Enhancement mode: V_{th} = 1.3 to 2.5 V (V_{DS} = 10 V, I_D = 1mA)

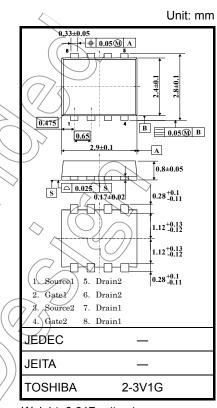
Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V _{DSS}	30	¥
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V _{DGR}	30	\searrow
Gate-source voltage		V _{GSS}	<u>4</u> 20	> v
Drain current	DC (Note 1)	I _D	4.2	А
	Pulse (Note 1)	I _{DP}	16.8	A
Drain power dissipation (t = 5 s) (Note 2a)	Single-device operation (Note 3a)	P _{D (1)}	1.48	
	Single-device value at dual operation (Note 3b)	P _D (2)	1.23	×
Drain power dissipation (t = 5 s) (Note 2b)	Single-device operation (Note 3a)	(PD (1))	0.58	
	Single-device value at dual operation (Note 3b)	PD (2)	0.36	
Single pulse avalanche energy (Note 4)		Eas <	2.86	mJ
Avalanche current		IAR	2.1	А
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		Ear	0.12	mJ
Channel temperature		, Tqh	150	°C
Storage temperature range		Tstg	-55~150	°C

Note: For Notes 1 to 6, refer to the next page.

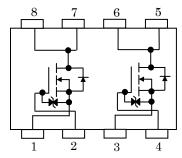
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with caution.

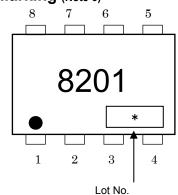


Weight: 0.017 g (typ.)

Circuit Configuration



Marking (Note 6)

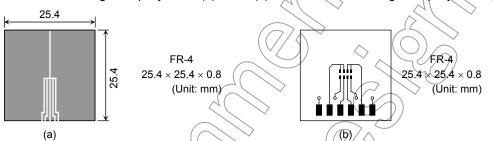


Thermal Characteristics

Characteristics		Symbol	Max	Unit	
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	84.5	°C/W	
(t = 5 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	101.6	0/11	
Thermal resistance,	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	215.5	°C/W	
channel to ambient (t = 5 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	347.2		

Note 1: The channel temperature should not exceed 150°C during use.

Note 2: (a) Device mounted on a glass-epoxy board (a) (b) Device mounted on a glass-epoxy board (b)



- Note 3: a) The power dissipation and thermal resistance values shown are for a single device. (During single-device operation, power is only applied to one device.)
 - b) The power dissipation and thermal resistance values shown are for a single device. (During dual operation, power is evenly applied to both devices.)
- Note 4: $V_{DD} = 24 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$ (initial), $L = 0.5 \text{ mH}, \text{ R}_{G} = 25 \Omega, \text{ I}_{AR} = 2.1 \text{ A}$
- Note 5: Repetitive rating: pulse width limited by maximum channel temperature.
- Note 6: on the lower left of the marking indicates Pin 1.
 - * Weekly code (3 digits):

U Week of manufacture

- (01/for the first week of the year, continuing up to 52 or 53)

Year of manufacture

(The last digit of the calendar year)

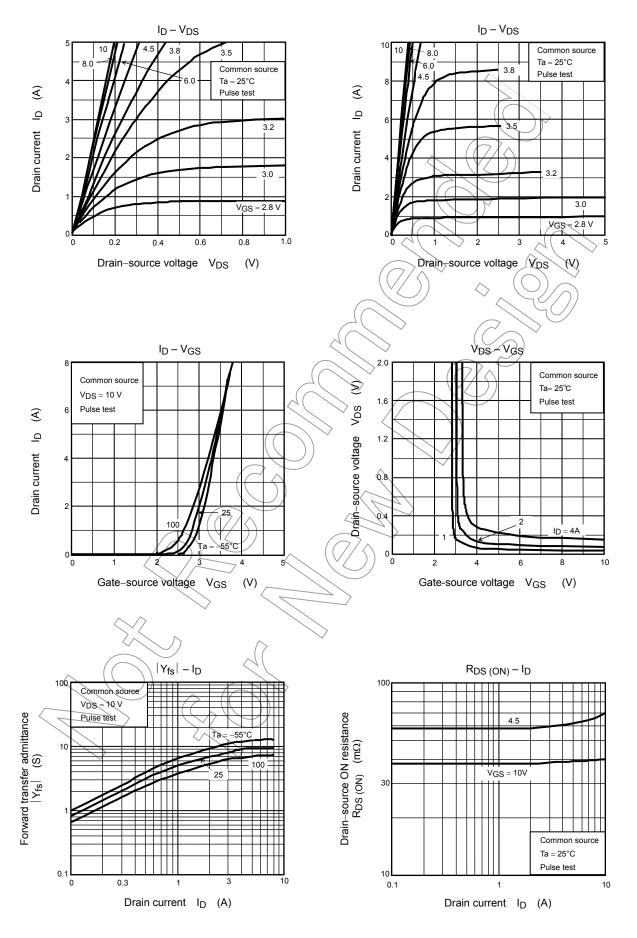
Electrical Characteristics (Ta = 25°C)

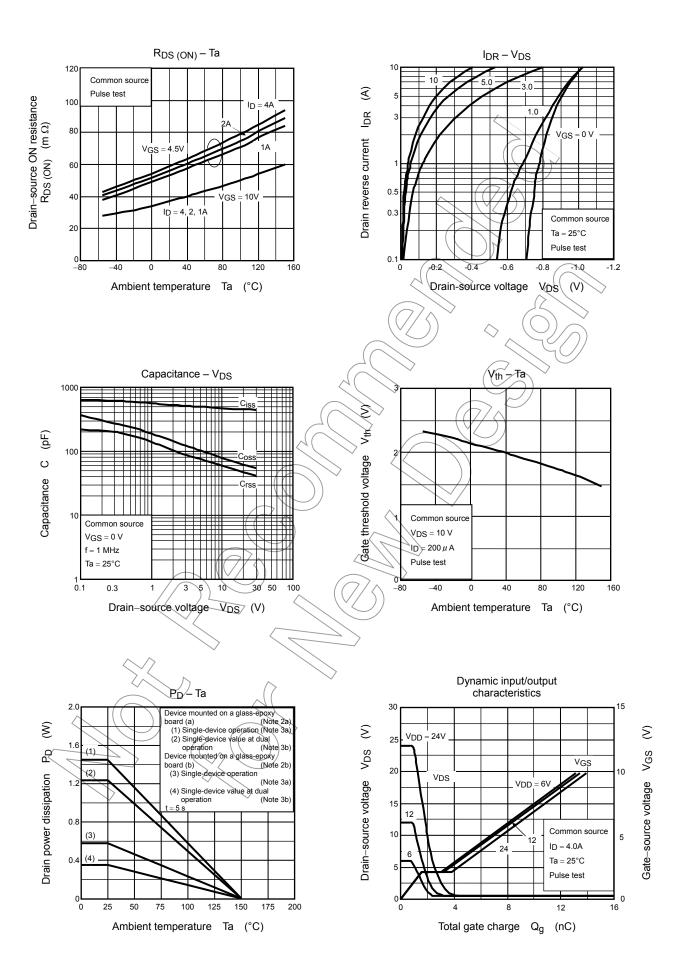
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage current		I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μA	
Drain cut-off current		I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	\mathcal{A}		10	μA	
Drain-source breakdown voltage		V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	(30	4	_	V	
		V (BR) DSX	I _D = 10 mA, V _{GS} = -20 V	2_		v		
Gate threshold vo	oltage	V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	1.3		2.5	V	
Drain-source ON resistance			V _{GS} = 4.5 V, I _D = 2.1 A	92	58	77	m0	
		R _{DS (ON)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 2.1 \text{ A}$	>	38	50	mΩ	
Forward transfer admittance		Y _{fs}	V _{DS} = 10 V, I _D = 2.1 A	3.5	7.0	_	S	
Input capacitance		C _{iss}	$\langle \langle \rangle \rangle$	_	470	X		
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		60		pF	
Output capacitance		C _{oss}		-(C) 80			
Switching time	Rise time	tr	$V_{GS} = 2.1 \text{ A}$		5.2			
	Turn-on time	t _{on}		Ð	8.3			
	Fall time	tf) _	4.0	_	ns	
	Turn-off time	toff	$D_{\psi}ty \leq 1\%, t_{W} \geq 10 \ \mu s$	_	22			
Total gate charge (gate-source plus gate-drain)		Qg		_	10	_		
Gate-source charge 1		Qgs1	V _{DD} ≈ 24 V, V _{GS} = 10 V, I _D = 4.2 A	—	1.7	—	nC	
Gate-drain ("miller") charge		Q _{gd}		_	2.4	_		

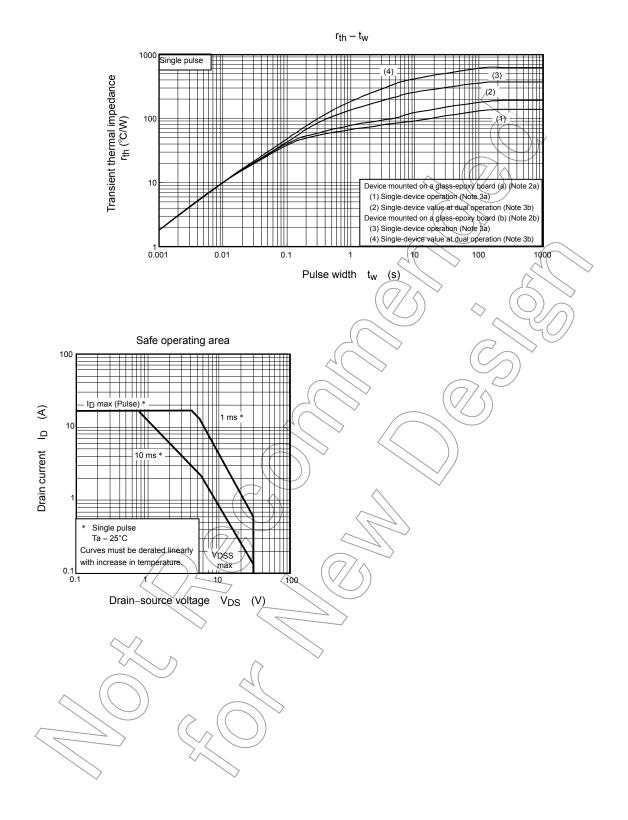
Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol Test Condition		Тур.	Max	Unit
Drain reverse current Pulse (Note 1)	IDRP —			16.8	А
Forward voltage (diøde)	V_{DSF} I_{DR} = 4.2 A, V_{GS} = 0 V			-1.2	V

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Handbook" etc.

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